

Call for Papers

Advanced Packaging Conference

19-20 October, Dresden, Germany
In conjunction with SEMICON Europa 2010

“Enabling Packaging Technologies for System Integration”

Semiconductor Equipment and Materials International (SEMI) invites Advanced Packaging professionals to submit abstracts for the conference, which will be held in conjunction with SEMICON Europa 19-21 October 2010 in Dresden, Germany.

The conference will give the opportunity to learn more about most important microelectronics applications developments which enable novel, advanced packaging Solutions to be the key drivers in system integration of electronic devices. The presentations should shed light on recent application specific packaging technologies, processing and manufacturing related technologies which can be leveraged as key enablers for cost efficient electronic devices and systems.

Presentations on original, non-commercial works describing recent developments are welcomed:

Advanced Packaging Market

- Application Drivers (Automotive, Power Electronics, ICT, Consumers, Live Science/Medical etc)
- Sensors (Opto-MEMS and integrated technologies etc)
- Lab on Chip / Biochips
- Microsystems
- Concentrated Solar Photovoltaics
- High-Brightness LED
- Fiber Optics

System Integration Technologies/ More than Moore

- System in Package (SIP) / 3D-Packaging
- Wafer Level Packaging (WLP) / fan-in and fan-out Packaging
- Through Silicon Vias (TSV)
- Package on Silicon
- MEMS/MST, System on Chip (SOP)
- Embedded Devices
- Equipment and Materials
- System Testing
- Device Performance tracking
 - Data Feedback Analysis
 - On-Line Testing

Instructions to submit an abstract – Submit the following information in an e-mail:

- Specify which topic your presentation addresses
- Presentation title
- Abstract of 200-400 words (descriptive paragraph identifying issue addressed and solution)
- Short biography of the author and picture
- Author contact details (Job title, company, address, telephone/e-mail)
- Contact person details i.e. Personal Assistant (Job title, company, address, telephone/e-mail)
- Indicate in subject box of e-mail: Advanced Packaging Conference Call for papers

Please submit ALL the above information in one e-mail by 30 April 2010 (extended deadline) to europrograms@semi.org

Your presentation will not be included in the review process unless the information is complete.

Evaluation criteria include significance, usefulness for the manufacturing world and clarity and accuracy as a paper. Abstracts will be peer-reviewed and selected relative to the points above. We encourage application related presentations, i.e. on joint projects between users and suppliers. Papers are to be non-commercial and focus on the technical/economical merits of a process rather than the individual company's product benefits.

Selected presenters will be notified by 28 May 2010.

SEMI Advanced Packaging Conference Committee: Andy Longford, PandA Europe (chairman); Jens Mueller, TU Ilmenau; Andreas Dill, Oerlikon; Andreas Fischer, Bosch; Mark Shaw, STMicroelectronics; Eef Bagerman, NXP; Eric Beyne, IMEC; Klaus Pressel, Infineon; Ignas van Dommelen, Elmos Advanced Packaging; Rolf Aschenbrenner, Fraunhofer IZM; Philip Homami, F+K Delvotec, Thomas Oppert, PAC Tech; Steffen Kroehnert, Nanium, Graham Jones, Henkel

For information on SEMICON Europa 2010, please visit www.semi.org/semiconeuropa or contact Carlos Lee, SEMI Europe Tel. +32.2.2896490